Evaluating the ADAQ23875 16-Bit, 15 MSPS µModule Data Acquisition Solution

FEATURES

- ADAQ23875 15 MSPS, 16-bit µModule evaluation board
- Versatile analog signal conditioning circuitry
- On-board reference, LDO, and power supply circuits
- PC software for control and data analysis of time and frequency domain
- System demonstration platform-compatible (SDP-H1)

EVALUATION BOARD KIT CONTENTS

- EVAL-ADAQ23875FMCZ evaluation board

EQUIPMENT NEEDED

- PC running Windows 10 or higher
- SDP-H1 (EVAL-SDP-CH1Z) controller board
- Low noise, precision signal source (such as the SYS-2700 series)
- Standard USB A to USB mini-B
- Band-pass filter suitable for 16-bit testing (value based on signal frequency)

SOFTWARE NEEDED

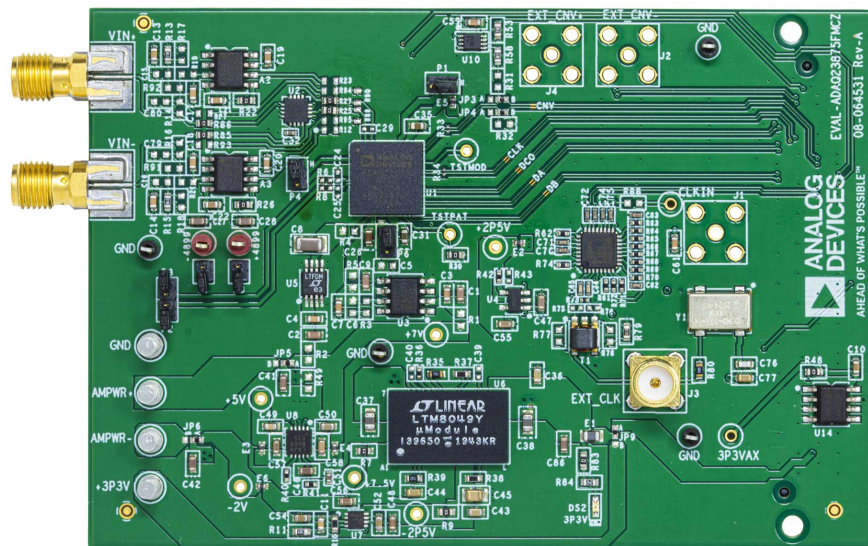- EVAL-ADAQ23875FMCZ ACE plug-in
- SDP-H1 driver

EVALUATION BOARD PHOTOGRAPH

GENERAL DESCRIPTION

The EVAL-ADAQ23875FMCZ evaluation board enables simplified evaluation of the ADAQ23875 15 MSPS, 16-bit, high speed, precision µModule® data acquisition solution. The evaluation board demonstrates the performance of the ADAQ23875 µModule and is a versatile tool for a variety of applications.

The ADAQ23875 µModule combines multiple common signal processing and conditioning blocks in a single device that includes a low noise, fully differential analog-to-digital converter (ADC) driver, a stable reference buffer, a high resolution, 16-bit, 15 MSPS successive approximation register (SAR) ADC, and the critical passive components necessary for optimum performance. A full description of this product is available in the ADAQ23875 data sheet, which must be consulted when using the evaluation board.

The EVAL-ADAQ23875FMCZ evaluation board interfaces with the high speed system demonstration platform, SDP-H1 (EVAL-SDP-CH1Z) via a 160-pin connector, as shown in Figure 2.

Figure 1.

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REVISION HISTORY
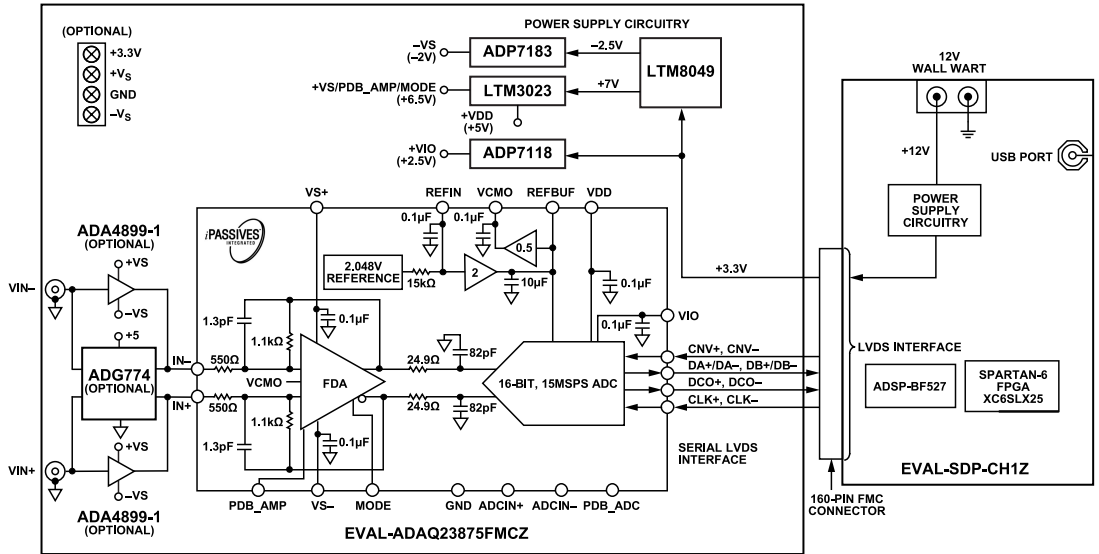
EVALUATION BOARD HARDWARE

Figure 2. Simplified Evaluation Block Diagram

SETTING UP THE EVALUATION BOARD

Figure 2 shows the simplified evaluation board block diagram of the EVAL-ADAQ23875FMCZ connected to the SDP-H1 controller board. The board consists of one µModule (U1, ADAQ23875), a choice of a 4.096 V reference (U5, LTC6655) or 2.048 V reference (U3, ADR4520), on-board power supplies to derive the necessary supply rails using the LTM8049 (U6), the ADP7118 (U4), the ADP7183 (U7), the LT3023 (U8), and an 800 MHz clock distribution IC (U13). The user also has an option to use the A2 and A3 amplifiers, such as the ADA4899-1 and the ADG774 (U2), when evaluating the ADAQ23875.

SDP-H1 CONTROLLER BOARD

The EVAL-ADAQ23875FMCZ evaluation board uses an SPI interface and is connected to the high speed controller board for the system demonstration platform (SDP-H1) controller board. The SDP-H1 board requires power from a 12 V wall adapter. The SDP-H1 has a Xilinx® Spartan 6 and an ADSP-BF527 processor with connectivity to the PC through a USB 2.0 high speed port. The controller boards allow the configuration and capture of data on the daughter boards from the PC via a USB.

The SDP-H1 has an FMC low pin count (LPC) connector with full differential LVDS and singled-ended LVCMOS support. It also features the 160-pin connector, found on the SDP-B, which exposes the Blackfin® processor peripherals. This connector provides a configurable serial, parallel I²C and SPI, and general-purpose input/output (GPIO) communications lines to the attached daughter boar for the functional description of the on-board power supplies.

POWER SUPPLIES

By default, all necessary supply rails on the EVAL-ADAQ23875FMCZ are powered by a 3.3 V rail coming from the SDP-H1 board. The EVAL-ADAQ23875FMCZ can be powered from

an external 3.3 V supply applied using the JP9 solder link if desired (see Table 2). The EVAL-ADAQ23875FMCZ positive rails, 7 V (+VS), 5 V (VDD), and 2.5 V (VIO), are generated from a combination of the power µModule, U6 (LTM8049), U4 (ADP7118-2.5), and a dual output LDO, U8 (LT3023). The EVAL-ADAQ23875FMCZ negative rail, −2.0 V (−VS), is generated by a combination of the power µModule, U6 (LTM8049), and U7 (ADP7183). Each supply rail includes necessary decoupling capacitors placed closed to the device. A single ground plane is used on this board to minimize the effect of high frequency noise interference.

Table 1. On-Board Power Supplies

Power Supply (V)	Function
+7.5, −2.5	Supply rails using the LTM8049
+7 (default)	VS+ rail using the LT3023
−2 (default)	VS− rail using the ADP7183
+2.5	VIO rail using the ADP7118
+5	VDD rail using the LT3023

ANALOG INPUTS

The SMA connectors on the EVAL-ADAQ23875FMCZ (VIN+ and VIN−) provide analog inputs from a low noise, audio precision signal source (such as the SYS-2700 or the SYS-x555 series). There are three options available to feed analog inputs directly to the ADG774, the ADA4899-1, and the ADAQ23875, as shown in Figure 21. To test the multiplexed functionality using the ADG774 (U2) CMOS multiplexer in front of the ADAQ23875 (U1), the positive and negative differential inputs of the ADG774 are switched continuously to generate a full-scale step. The optional amplifiers, ADA4899-1 (A2, A3), can be set up in a unity-gain configuration driving the ADAQ23875. In a default configuration of board, an input signal via VIN+ and VIN− can be fed directly to the ADAQ23875 by bypassing U2, A2, and A3.

EVALUATION BOARD HARDWARE

The EVAL-ADAQ23875FMCZ is factory configured to provide the appropriate input signal type, single-ended or fully differential, and different gain/attenuation or input range scaling. Table 2 lists the necessary jumper positions and link options for different configurations. The default board configuration presents 4.096 V on the REFBUF pin. The default board configuration also presents a buffered 2.048 V (midscale) at the VCMO pin of the FDA on the ADAQ23875.

To evaluate dynamic performance, a fast Fourier transform (FFT), integral nonlinearity (INL), differential nonlinearity (DNL), or time domain (waveform, histogram) test can be performed by applying a very low distortion ac source (see Figure 14 to Figure 18). For

low input frequency testing below 100 kHz, it is recommended to use a low noise, audio precision signal source (such as the SYS-2700 series) with the outputs set to balanced floating. A different precision signal source can be used alternatively with additional band-pass filtering. The filter bandwidth depends on input bandwidth of interest.

LINK CONFIGURATION OPTIONS

Multiple link options must be set correctly for the appropriate operating setup before applying the power and signal to the EVAL-ADAQ23875FMCZ. Table 2 shows the default link positions for the EVAL-ADAQ23875FMCZ.

Table 2. Link Options for the EVAL-ADAQ23875FMCZ

Link	Default	Function	Comment
JP3	Center to B	FPGA CNV+	Change center to A when using ADC_PLL_CNV+.
JP4	Center to B	FPGA CNV−	Change center to A when using ADC_PLL_CNV−.
JP5	Center to A	AMP+	Change center to B when using an external supply.
JP6	Center to A	AMP−	Change center to B when using an external supply. If configured to single supply VS− to GND, remove both jumpers (JP6) and install R49 (0 Ω).
JP9	Center to A	3.3 V	Change center to B when using an external 3.3 V supply.
P1	Tie Pin 2 and Pin 3 (connected to GND)	Two-lane digital output modes	Digital input that enables two-lane output mode. Use this jumper to select either single-lane or two-lane data output mode. The default setting is Pin 2 and Pin 3. The Pin 2 and Pin 3 setting clocks out all data on the DA± pin. The Pin 1 and Pin 2 setting clocks out data alternately on the DA± and DB± pins.
P2	No connect	ADCIN−	Negative input of an internal ADC. Extra capacitance can be added on this pin to reduce the RC filter bandwidth. Optional for the ADAQ23875.
P3	No connect	ADCIN+	Positive input of an internal ADC. Additional capacitance can be added on this pin to reduce the RC filter bandwidth. Optional for the ADAQ23875.
P4	Tie Pin 1 and Pin 2	PDB_AMP	Active low. Connect this pin to GND to power-down the fully differential ADC driver. Otherwise, connect it to VS+.
P5	Not applicable	SDP-H1 FMC connector	The EVAL-ADAQ23875FMCZ board interfaces to the SDP-H1 board via a 160-pin connector.
P6	Tie Pin 1 and Pin 2	PDB_ADC	Digital input that enables the power-down mode. When PDB_ADC is low, an internal ADC core enters power-down mode, and all circuitry (including the LVDS interface) is shut down. When PDB_ADC is high, the device operates normally. Logic levels are determined by VIO.
P7	0 Ω installed	−VS for the ADA4899-1 (A2, A3)	Remove 0 Ω to use the external supply for the ADA4899-1 (A2, A3).
P8	0 Ω installed	+VS for the ADA4899-1 (A2, A3)	Remove 0 Ω to use the external supply for the ADA4899-1 (A2, A3).

EVALUATION BOARD CONNECTORS

The functional descriptions for all the connectors (including a 160-pin FMC connector used to interface with the SDP-H1) used on the EVAL-ADAQ23875FMCZ are listed in Table 2 and Table 3, respectively.

There are several test points and single in line (SIL) headers on the EVAL-ADAQ23875FMCZ. These test points provide easy access to on-board signals for troubleshooting and evaluation purposes.

Table 3. On-Board Connectors

Connector	Function
J1	CLKIN input
J2	EXT_CNV−
J3	External CLK input
J4	EXT_CNV+
VIN+	Analog input V+
VIN−	Analog input V−
+3P3V	External power supply
P5	SDP-H1 FMC connector

Table 4. 160-Pin FMC Connector (P5) Details

Signals	Function
OSC_CLK+	100 MHz low jitter positive line of differential pair for carrying clock signals from the daughter board.
OSC_CLK−	100 MHz low jitter negative line of differential pair for carrying clock signals from the daughter board.
CLK±	ADAQ23875 CLK input signals connected to FPGA Bank 2.[1, 2]
CLK−	ADAQ23875 CLK input signals connected to FPGA Bank 2.[1, 2]
DCO+	Positive line of differential pair for carrying clock signals from the daughter board.
DCO−	Negative line of differential pair for carrying clock signals from the daughter board.
FPGA_CNV+	User defined signals connected to FPGA Bank 2.[1, 2]
FPGA_CNV−	User defined signals connected to FPGA Bank 2.[1, 2]
DA±	User defined signals connected to FPGA Bank 2.[1]
DB±	User defined signals connected to FPGA Bank 2.[1]
+3P3V_FMC	3.3 V (3 A) power supply to daughter board.
SCL	I²C clock line for reading FMC EEPROM.
SDA	I²C data line for reading FMC EEPROM.
GA0	I²C geographical Address 0. Must be connected to Address Pin A1 of the FMC EEPROM.
GA1	I²C geographical Address 1. Must be connected to Address Pin A0 of the FMC EEPROM.
3P3VAUX	3.3 V (20 mA) power supply for powering only the FMC EEPROM.
PG_C2M	Active high signal indicating that the 12P0V, 3P3V, and VADJ power supplies are turned on.
CNV_EN	User defined signals connected to FPGA Bank 2.[1]

[1] User defined signals with a P suffix can be used as the positive pin of the differential pair. User defined signals with an N suffix can be used as the negative pin of the differential pair. For further information, see the VITA 57 specification.

[2] User defined signals with a CC suffix are the preferred signal lines on which to transmit clock signals from the controller board to the daughter board. These signal lines are connected to global clock lines on the FPGA, but they can also be used to carry any other user defined signal. For further information, see the VITA 57 specification.

SOFTWARE INSTALLATION

Before using the EVAL-ADAQ23875FMCZ, download and install the ACE (Analysis, Control, Evaluation) software. Download the software from https://www.analog.com/ en/design-center/evaluation-hardware-and-software/ace-software.html.

ACE is a desktop software application allowing the evaluation and control of multiple evaluation systems across the Analog Devices product portfolio. The installation process consists of the ACE software installation and the SDP-H1 driver installation.

To ensure that the evaluation system is correctly recognized when it is connected to the PC, install the ACE software and the SDP-H1 driver before connecting the EVAL-ADAQ23875FMCZ and the SDP-H1 board to the USB port of the PC.

INSTALLING THE ACE SOFTWARE

To install the ACE software, take the following steps:

1. Download the ACE software to a Windows-based PC.
2. Double-click the **ACEInstall.exe** file to begin the installation. By default, the software is saved to the following location: **C:\Program Files (x86)\Analog Devices\ACE.**
3. A dialog box appears asking for permission to allow the program to make changes to the PC. Click **Yes** to begin the installation process.
4. Click **Next >** to continue the installation, as shown in Figure 3.
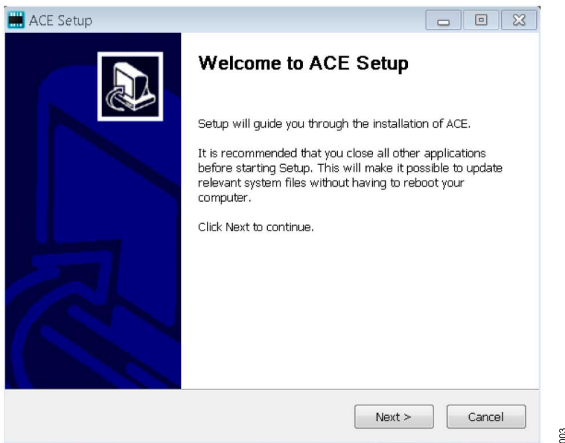
Figure 3. Evaluation Software Install Confirmation

5. Read the software license agreement and click **I Agree** (see Figure 4).

Figure 4. License Agreement

6. Choose an installation location and click **Next >** (see Figure 5).
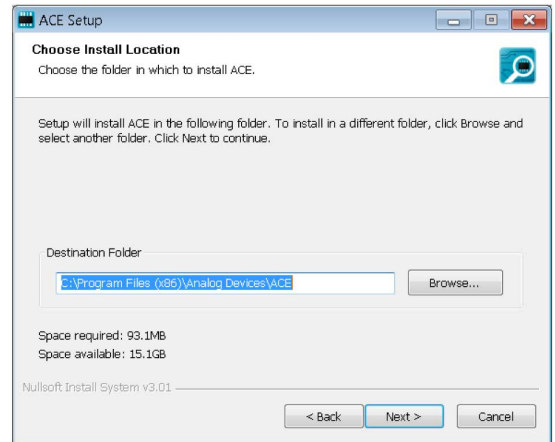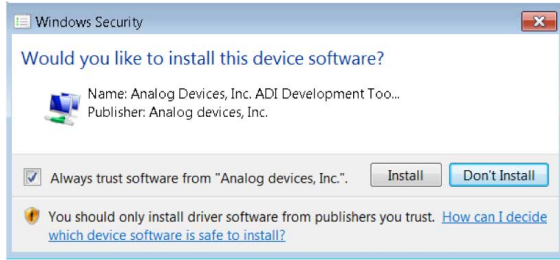

Figure 5. Choose Install Location

7. Select the **PreRequisites** checkbox to include the installation of the SDP-H1 driver. Click **Install** (see Figure 6).
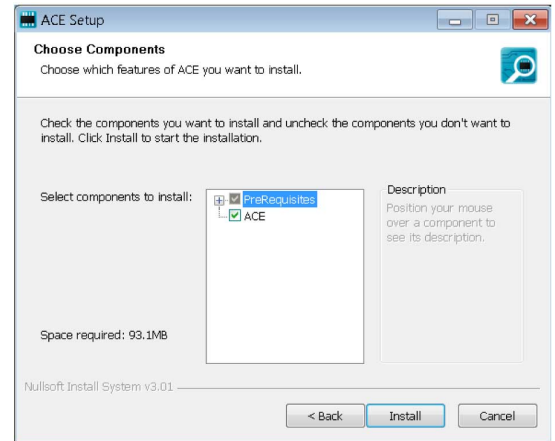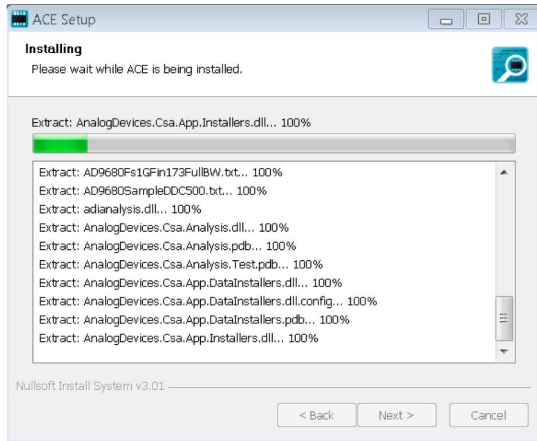

Figure 6. Choose Components

8. The **Windows Security** window appears. Click **Install** (see Figure 7). The installation is in progress. No action is required (see Figure 8).
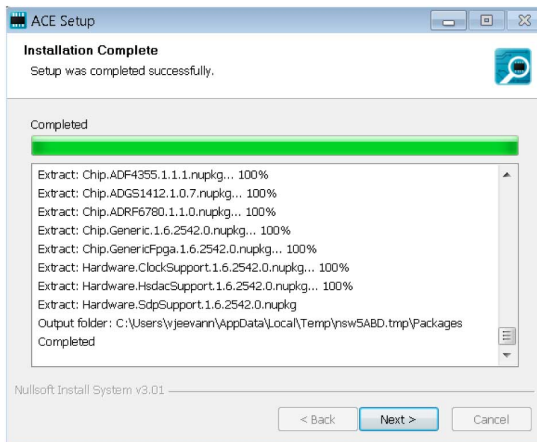
SOFTWARE INSTALLATION

Figure 7. Windows Security Window

Figure 8. Installation in Progress

9. The installation is complete (see Figure 9). Click **Next >** and then click **Finish** to complete the installation.

Figure 9. Installation Complete

SOFTWARE OPERATION

LAUNCHING THE SOFTWARE

When the EVAL-ADAQ23875FMCZ and SDP-H1 boards are properly connected to the PC, launch the ACE software. To launch the ACE software, take the following steps:

1. From the **Start** menu, select **All Programs > Analog Devices > ACE > ACE.exe** to open the main software window shown in Figure 10.
2. The EVAL-ADAQ23875FMCZ icon appears in the **Attached Hardware** section.
3. If the EVAL-ADAQ23875FMCZ is not connected to the USB port via the SDP-H1 board when the software is launched, the EVAL-ADAQ23875FMCZ board icon does not appear in the **Attached Hardware** section. Connect the EVAL-ADAQ23875FMCZ and SDP-H1 board to the USB port of the PC and wait a few seconds, then continue following these instructions.
4. Double-click the EVAL-ADAQ23875FMCZ board icon to open the window shown in Figure 10.
5. Click **Software Defaults** and then click **Apply Changes**.
6. Click **Proceed to Analysis** to open the EVAL-ADAQ23875FMCZ analysis shown in Figure 11.

EXITING THE SOFTWARE

To exit the software, click file icon on the upper right tab and then click **Exit**.

DESCRIPTION OF ANALYSIS WINDOW

Click **Proceed to Analysis** in the chip view window to open the window shown in Figure 14. The analysis view contains the **Waveform** tab, **Histogram** tab, **FFT** tab, **INL** tab, and **DNL** tab.

Waveform Tab

The **Waveform** tab displays results in time domain, as shown in Figure 14. The **Capture** pane contains the capture settings, which reflect in the registers automatically before data capture.

Capture Pane

The **Sample Count** dropdown list in the **General Capture Settings** section allows the user to select the number of samples per channel per capture.

The user can enter the input sample frequency in kSPS in the **Sampling Frequency (KSPS)** box in the **General Capture Settings** section. Refer to the ADAQ23875 data sheet to determine the maximum sampling frequency for the selected mode.

Click **Run Once** in the **Device Settings** section to start a data capture of the samples at the sample rate specified in the **Sample Count** dropdown list. These samples are stored on the FPGA device and are only transferred to the PC when the sample frame is complete.

Click **Run Continuously** in the **Device Settings** section to start a data capture that gathers samples continuously with one batch of data at a time.

Results Pane

The **Display Channels** section allows the user to select which channels to capture. The data for a specific channel is only shown if that channel is selected before the capture.

The **Waveform Results** section displays amplitude, sample frequency, and noise analysis data for the selected channels.

Click **Export** to export captured data. The waveform, histogram, and FFT data is stored in .xml files, along with the values of parameters at capture.

Waveform Graph

The data waveform graph shows each successive sample of the ADAQ23875 output. The user can zoom in on and pan across the waveform using the embedded waveform tools. The channels to display can be selected in the **Display Channels** section**.**

Click the display unit's dropdown list (shown with the **Codes** option selected in Figure 14) to select whether the data graph displays in units of hexadecimal, volts, or codes. The axis controls are dynamic.

When selecting either y-scale dynamic or x-scale dynamic, the corresponding axis width automatically adjusts to show the entire range of the ADAQ23875 results after each batch of samples.

Histogram Tab

The **Histogram** tab contains the histogram graph and the **Results** pane, as shown in Figure 15.

The **Results** pane displays the information related to the dc performance.

The histogram graph displays the number of hits per code within the sampled data. This graph is useful for dc analysis and indicates the noise performance of the device.

FFT Tab

The **FFT** tab displays FFT information for the last batch of samples gathered, as shown in Figure 16. The FFT also allows the oversampling function with OSR up to 256×, as shown in Figure 19. As a general rule, oversampling by a factor of four provides one additional bit of resolution, or a 6 dB increase in dynamic range (DR) of the ADAQ23875. In other words,

$$\Delta DR = 10 \times \log 10\,(OSR)\ \text{(in dB)}$$

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INL, DNL Tab

The **INL** and **DNL** tab displays linearity analysis. INL is the deviation of each individual code from a line drawn from negative full scale through positive full scale. The point used as negative full scale occurs ½ LSB before the first code transition. Positive full scale is defined as a level 1½ LSB beyond the last code transition. The deviation is measured from the middle of each code to the true straight line.

In an ideal ADC, code transitions are 1 LSB apart. DNL is the maximum deviation from this ideal value. DNL is often specified in terms of resolution for which no missing codes are guaranteed.

To perform a linearity test, apply a sinusoidal signal with 0.5 dB above full scale to the EVAL-ADAQ23875FMCZ board at the VIN+ and VIN− Subminiature Version A (SMA) inputs. Set the number of hits per code and adjust to the desired accuracy. Using a large number of hits per code results in a significant test time. Figure 17 and Figure 18 display captured data that includes the ±INL and ±DNL positions.

Analysis Pane

The **General Settings** section allows the user to set up the preferred configuration of the FFT analysis. This configuration sets how many tones are analyzed and if the fundamental is set manually.

The **Windowing** section allows the user to set up the preferred windowing type to use in the FFT analysis and the number of harmonic bins and fundamental bins that must be included in the analysis.

The **Single Tone Analysis** and the **Two-Tone Analysis** sections sets up the fundamental frequencies included in the FFT analysis. When one frequency is analyzed, use the **Single Tone Analysis** section. When two frequencies are analyzed, use the **Two-Tone Analysis** section.

Results Pane

The **Signal** section displays the sample frequency, fundamental frequency, and fundamental power.

The **Noise** section displays the signal-to-noise ratio (SNR) and other noise performance results.

The **Distortion** section displays the harmonic content of the sampled signal and dc power when viewing the FFT analysis.
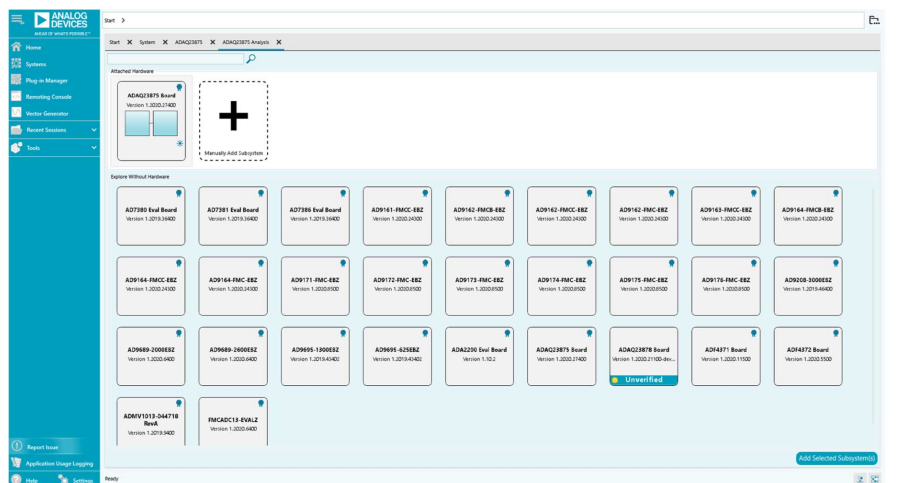
Figure 10. EVAL-ADAQ23875FMCZ ACE Software Main Window

SOFTWARE OPERATION
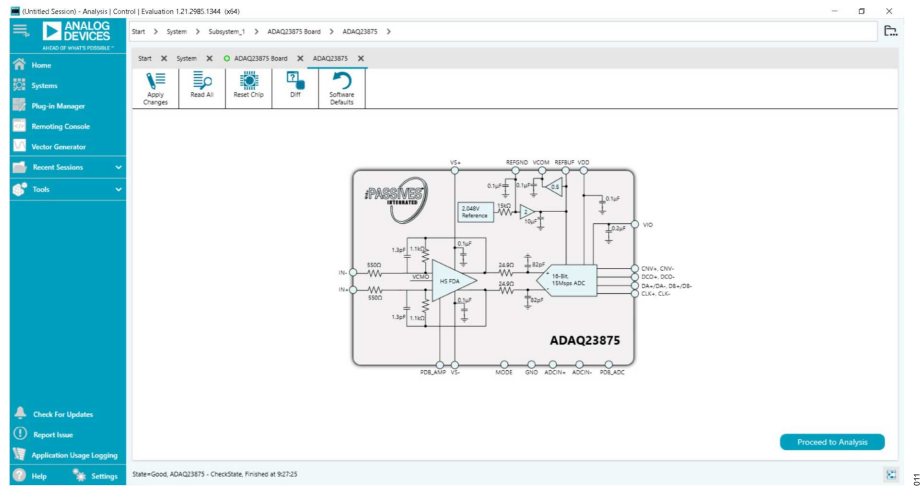
Figure 11. EVAL-ADAQ23875FMCZ Board View
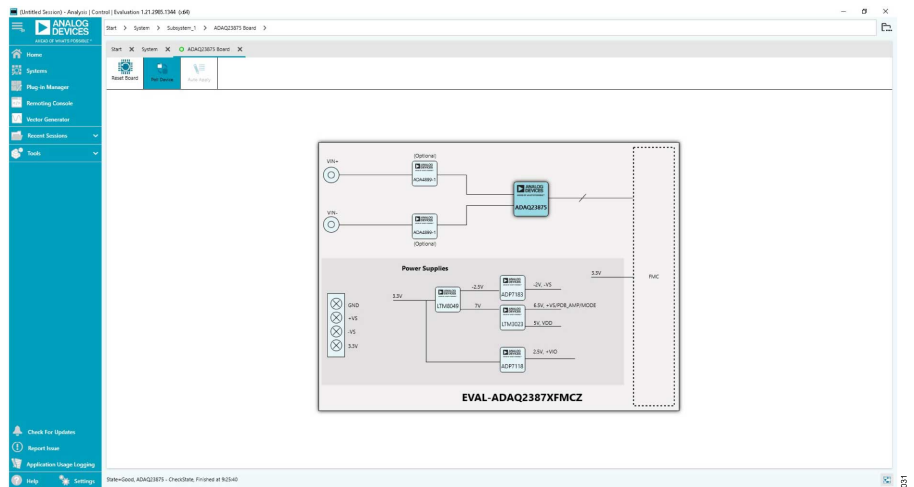
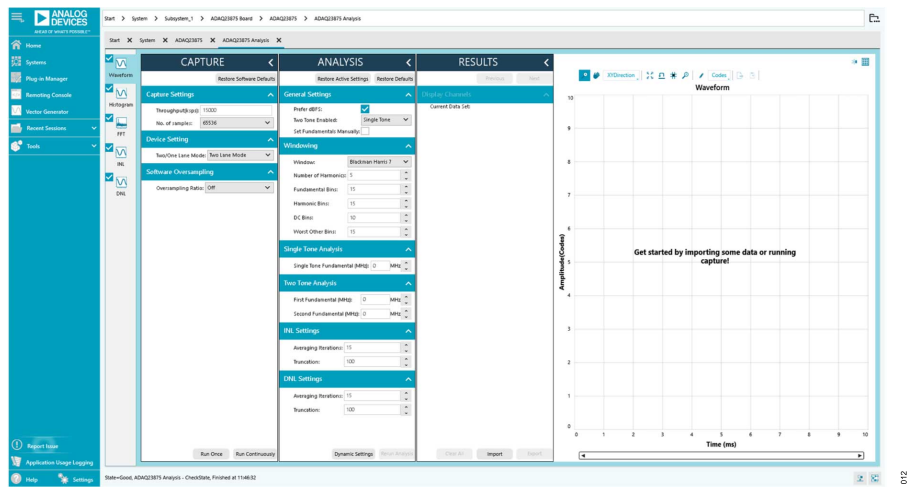Figure 12. EVAL-ADAQ23875FMCZ Chip View

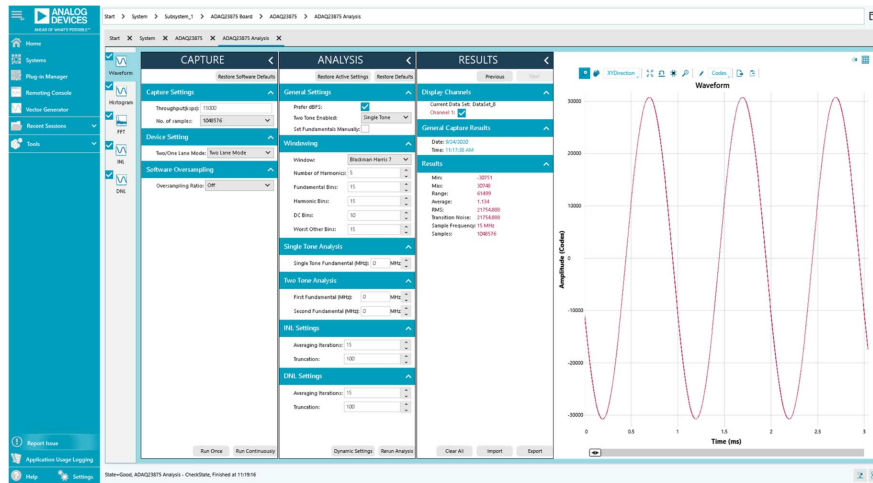Figure 13. EVAL-ADAQ23875FMCZ Analysis View

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Figure 14. EVAL-ADAQ23875FMCZ Waveform
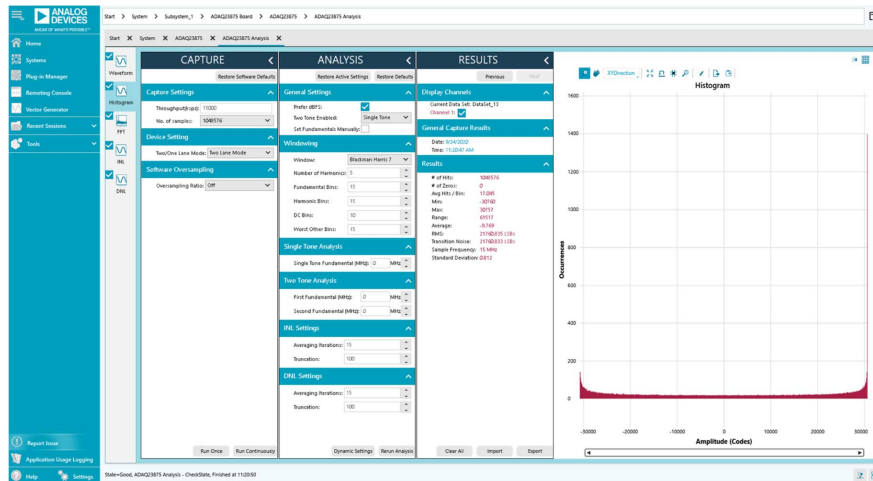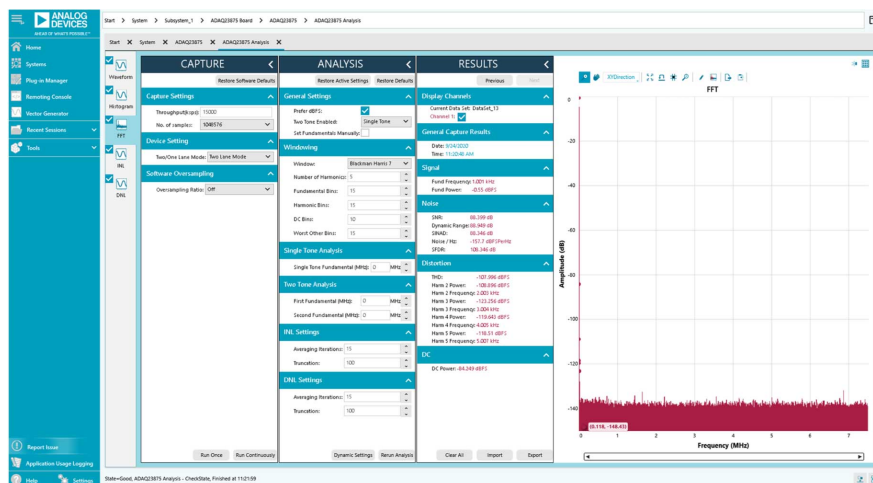

Figure 15. EVAL-ADAQ23875FMCZ Histogram

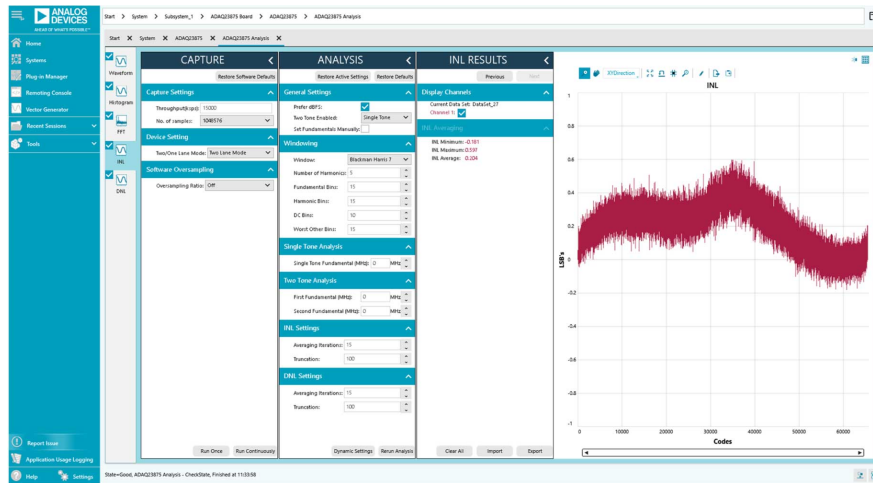*Figure 16. EVAL-ADAQ23875FMCZ FFT*

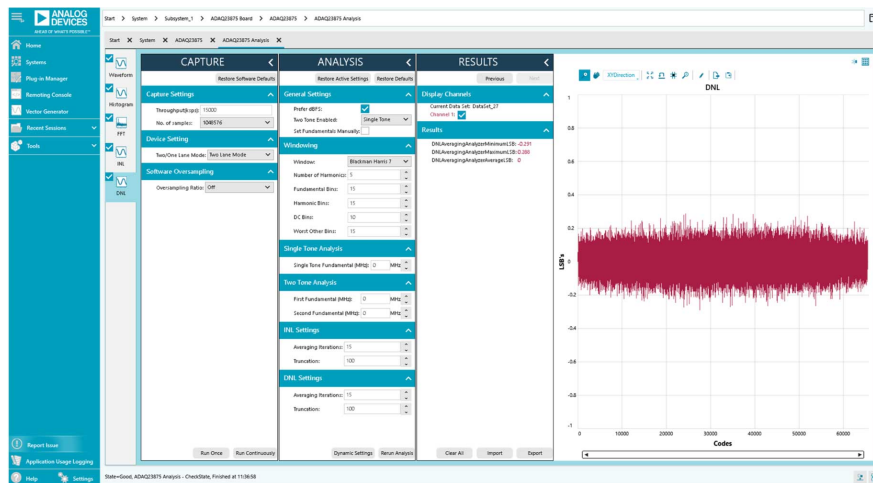## SOFTWARE OPERATION

Figure 17. EVAL-ADAQ23875FMCZ INL

Figure 18. EVAL-ADAQ23875FMCZ DNL

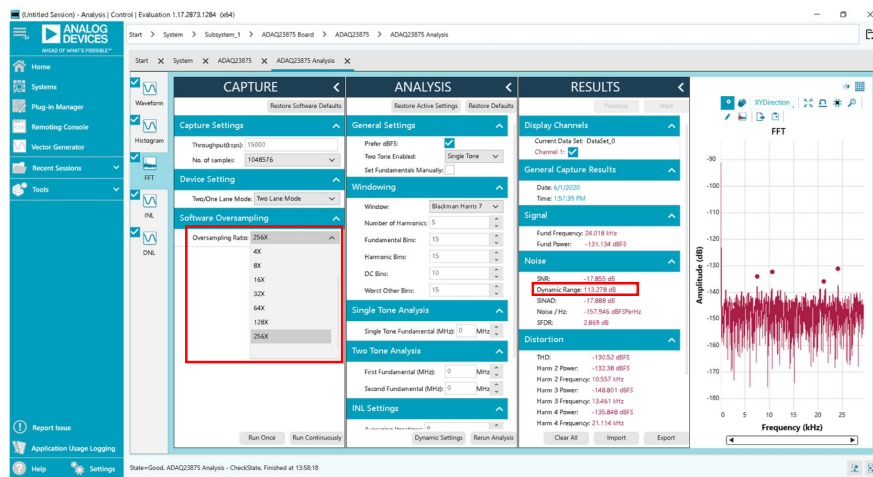*Figure 19. EVAL-ADAQ23875FMCZ FFT with an Oversampling Rate (OSR) of 256×, Inputs Shorted*

TROUBLESHOOTING

The SDP-H1 board is the communication link between the PC and the EVAL-ADAQ23875FMCZ. Figure 2 shows a diagram of the connections between the EVAL-ADAQ23875FMCZ and the SDP-H1 board.

To ensure that the evaluation system is correctly recognized when it is connected to the PC, install the ACE software and the SDP-H1 driver before connecting the EVAL-ADAQ23875FMCZ and the SDP-H1 board to the USB port of the PC.

When the software installation is complete, set up the EVAL-ADAQ23875FMCZ and the SDP-H1 board as described in the following sections.

CONNECTING THE EVAL-ADAQ23875FMCZ AND THE SDP-H1 TO THE PC

To connect the EVAL-ADAQ23875FMCZ and the SDP-H1 board to the PC, take the following steps:

1. Ensure that all configuration links are in the appropriate positions, as described in Table 1.
2. Connect the EVAL-ADAQ23875FMCZ securely to the 160-way connector on the SDP-H1 board. The EVAL-ADAQ23875FMCZ does not require an external power supply adapter.
3. Connect the SDP-H1 board to the PC via the USB cable enclosed in the SDP-H1 kit. Refer to Figure 2.

VERIFYING THE BOARD CONNECTION

To verify the board connection, take the following steps:

1. Allow the found new hardware wizard to run after the SDP-H1 board is plugged in to the PC. If using Windows XP®, search for the SDP-H1 drivers. Choose to automatically search for the drivers for the SDP-H1 board if prompted by the operating system.
2. A dialog box may appear asking for permission to allow the program to make changes to the computer. In this case, click **Yes**. The **Computer Management** window opens.
3. Under **System Tools**, click **Device Manager** and use the **Device Manager** window to ensure that the EVAL-ADAQ23875FMCZ is connected to the PC properly.
4. If the SDP-H1 driver software is installed and the board is connected to the PC properly, **Analog Devices SDP-H1** appears under **ADI Development Tools** in the **Device Manager** window, as shown in Figure 20.
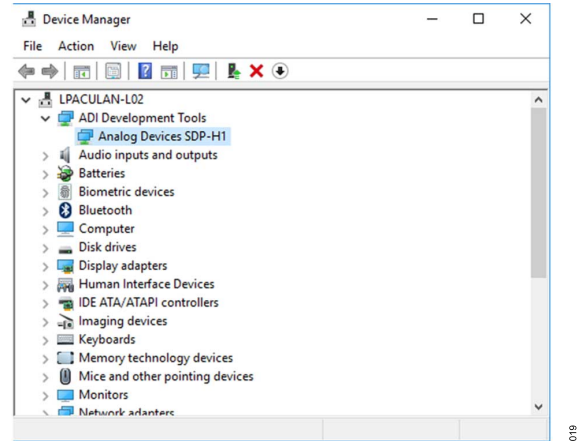

Figure 20. Windows Device Manager

DISCONNECTING THE EVAL-ADAQ23875FMCZ

Always remove power from the SDP-H1 board or click the reset tact switch located along the mini USB port before disconnecting the EVAL-ADAQ23875FMCZ from the SDP-H1 board.

BOARD LAYOUT GUIDELINES

The printed circuit board (PCB) layout is critical for preserving signal integrity and achieving the expected performance from the ADAQ23875. A multilayer board with an internal, clean ground plane in the first layer beneath the ADAQ23875 is recommended. Care must be taken with the placement of individual components and routing of various signals on the board. It is highly recommended to route input and output signals symmetrically. Solder the ground pins of the ADAQ23875 directly to the ground plane of the PCB using multiple vias. Remove the ground and power planes under the analog input/output and digital input/output pins of the ADAQ23875 (including F1 and F2) to avoid undesired parasitic capacitance. Any undesired parasitic capacitance may impact the distortion and linearity performance of the ADAQ23875.

The pinout of the ADAQ23875 eases layout and allows the analog signals on the left side and the digital signals on the right side. The sensitive analog and digital sections must be separated on the PCB while keeping the power supply circuitry away from the analog signal path. Fast switching signals, such as CNV± or CLK±, and the DA± and DB± digital outputs must not run near or cross over analog signal paths to prevent noise coupling to the ADAQ23875.

Good quality ceramic bypass capacitors of at least 2.2 µF (0402, X5R) must be placed from the output of the LDOs generating the µModule supply rails (VDD, VIO, VS+, and VS−) to GND to minimize electromagnetic interference (EMI) susceptibility and to reduce the effect of glitches on the power supply lines. All the other required bypass capacitors are laid out within the ADAQ23875, saving extra board space and cost. When the external decoupling capacitors on the REFIN, VDD, and VIO pins near the µModule are removed, there is no significant performance impact.

TROUBLESHOOTING

MECHANICAL STRESS

The mechanical stress of mounting a device to a board may cause subtle changes to the SNR and internal voltage reference. The best soldering method is to use IR reflow or convection soldering with a controlled temperature profile. Hand soldering with a heat gun or a soldering iron is not recommended.
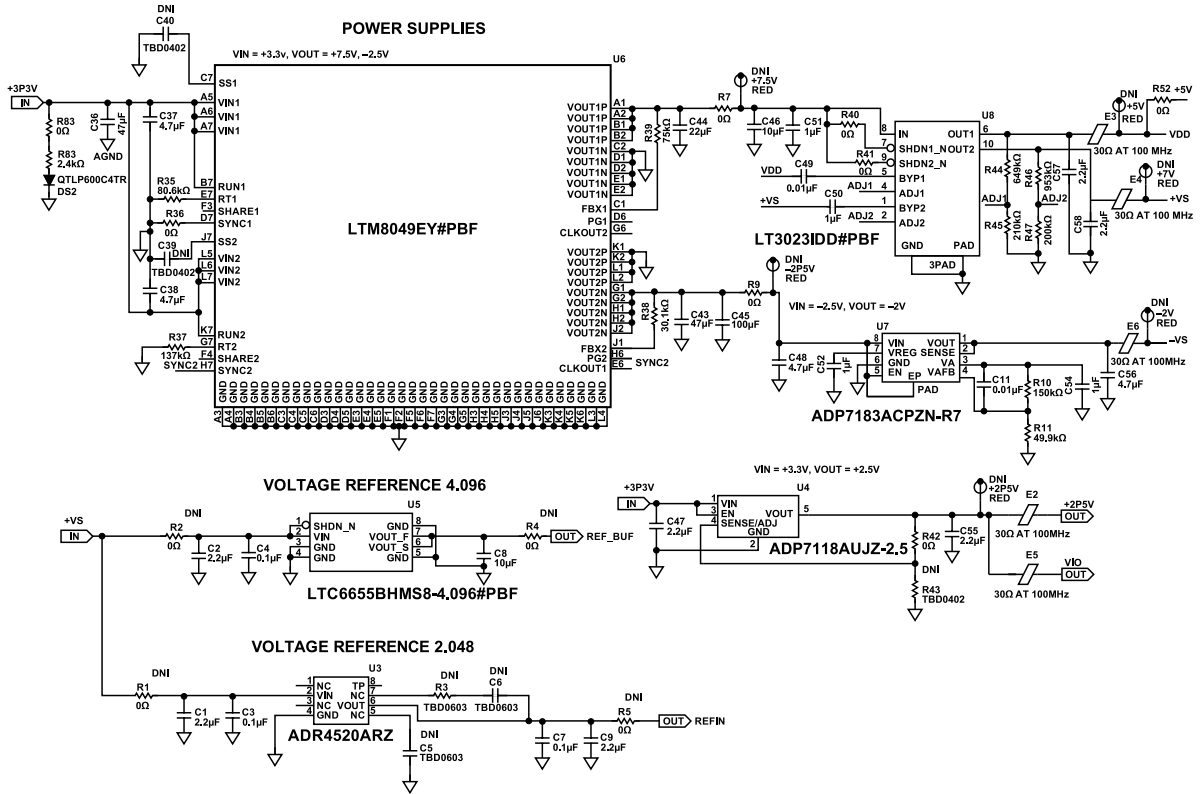
EVALUATION BOARD SCHEMATICS

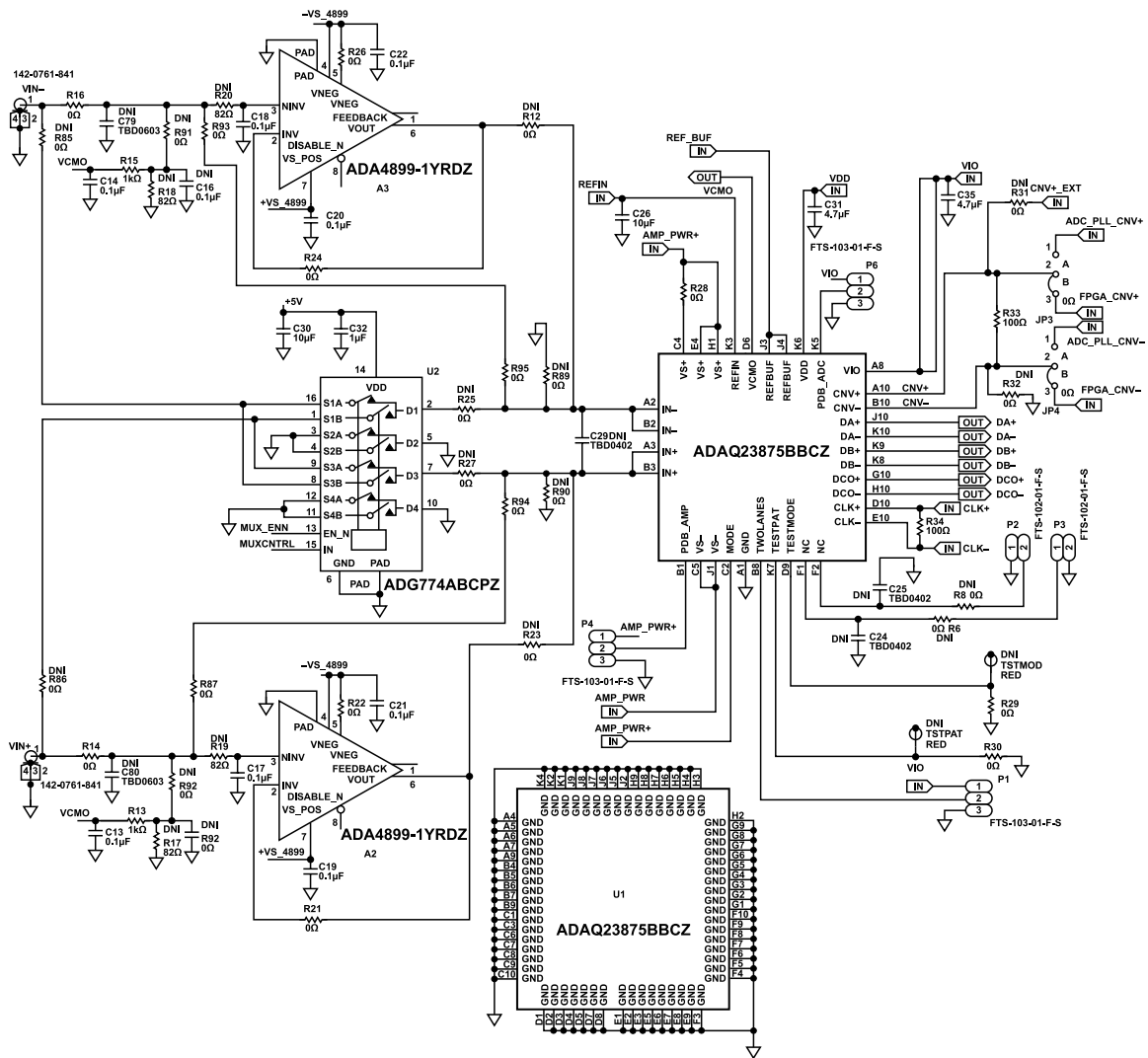*Figure 21. EVAL-ADAQ23875FMCZ Board Schematic, Power Supplies*

EVALUATION BOARD SCHEMATICS

Figure 22. EVAL-ADAQ23875FMCZ Board Schematic, Input Signal Path

EVALUATION BOARD SCHEMATICS
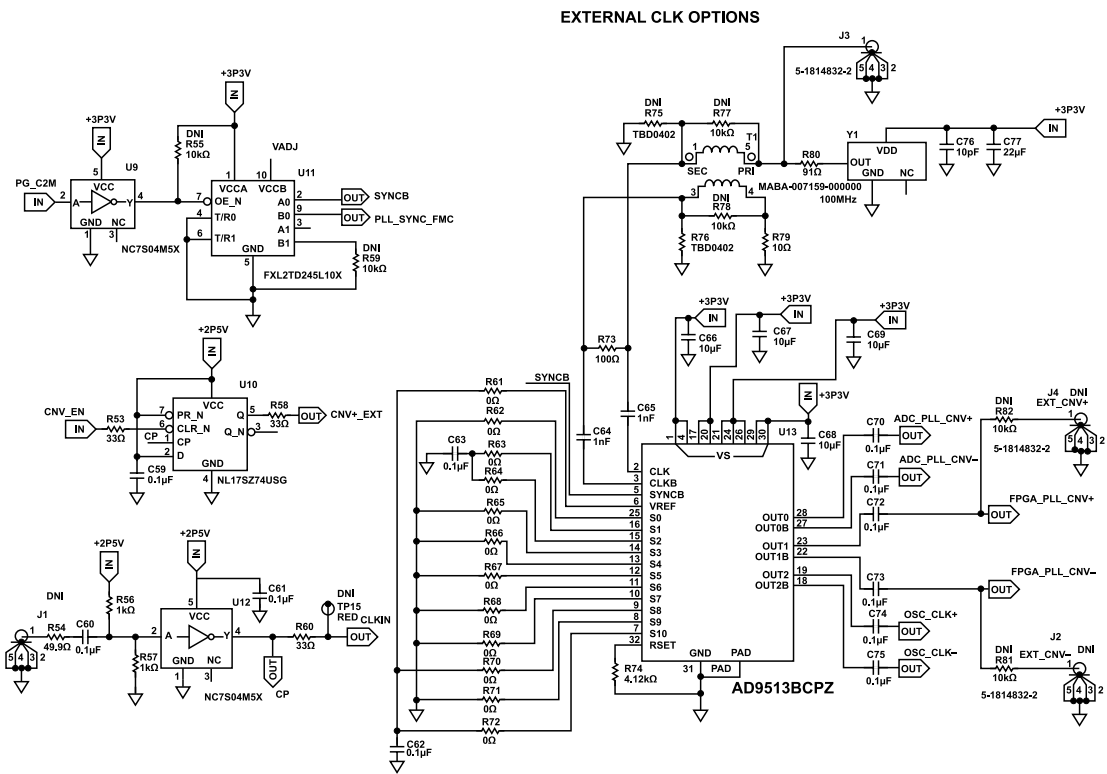
Figure 23. EVAL-ADAQ23875FMCZ Board Schematic, External Clock

EVALUATION BOARD SCHEMATICS
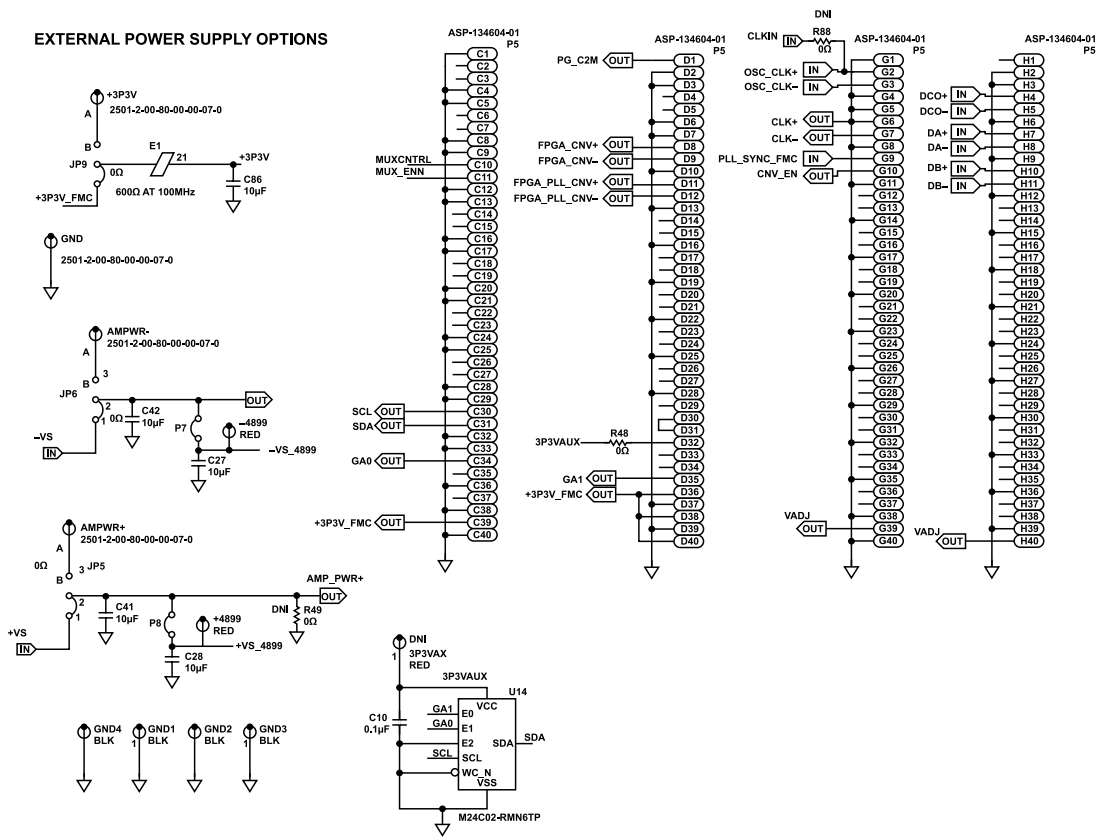
Figure 24. EVAL-ADAQ23875FMCZ Board Schematic, FMC Connector, and External Supplies
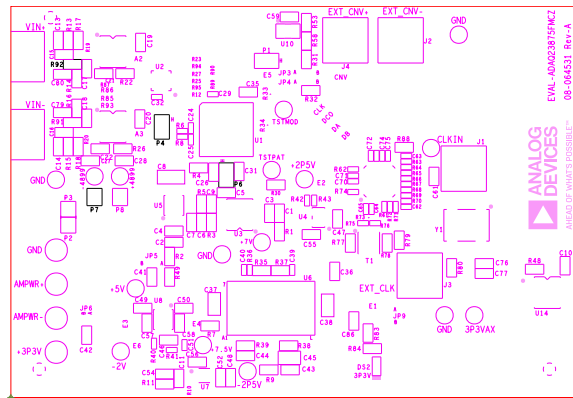
Figure 25. EVAL-ADAQ23875FMCZ Board Primary Silkscreen

EVALUATION BOARD SCHEMATICS
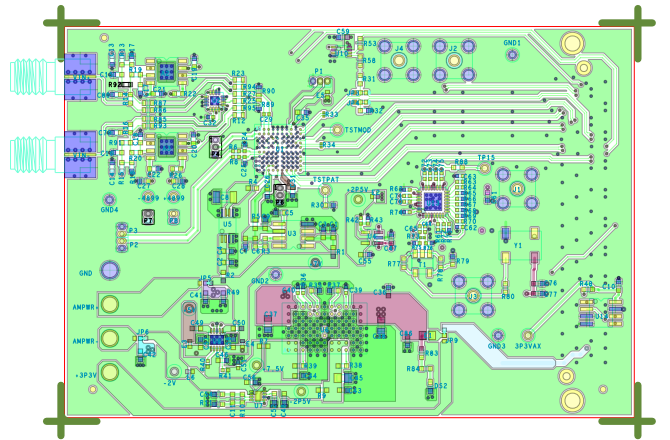
Figure 26. EVAL-ADAQ23875FMCZ Board Primary Layer, L1
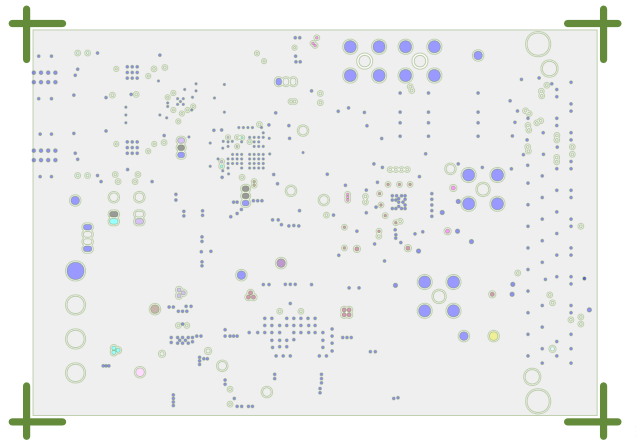
Figure 27. EVAL-ADAQ23875FMCZ Board Ground Layer, L2
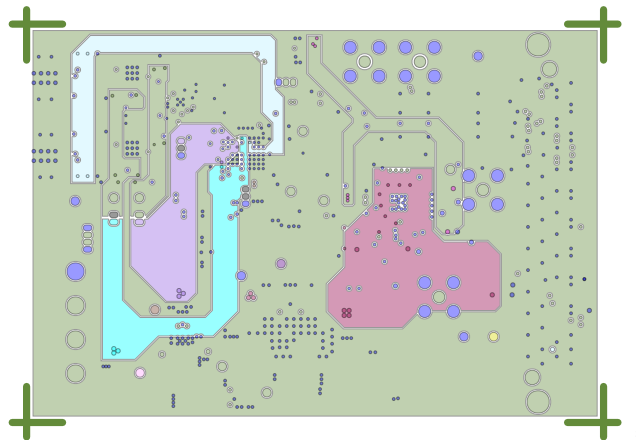
Figure 28. EVAL-ADAQ23875FMCZ Board Power Layer, L3

EVALUATION BOARD SCHEMATICS
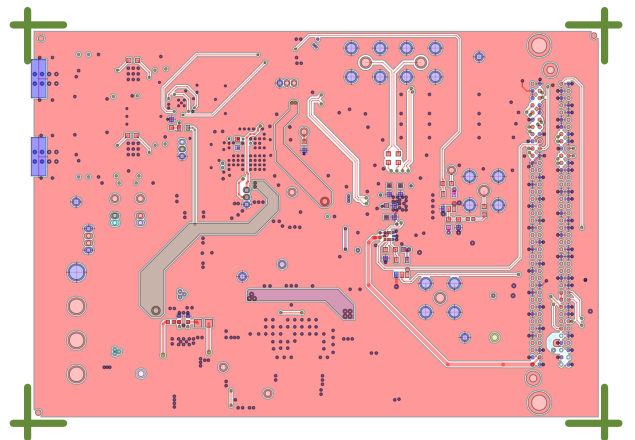
Figure 29. EVAL-ADAQ23875FMCZ Board Bottom Layer, L4
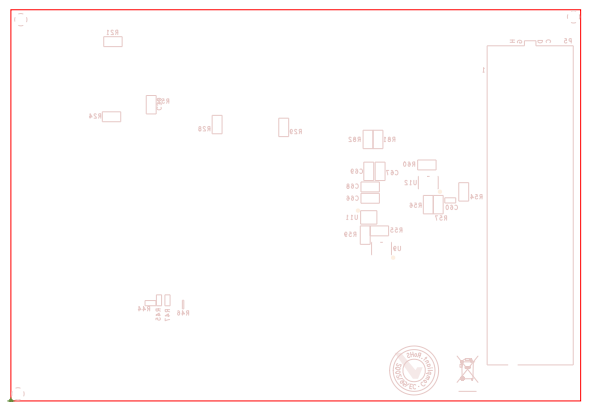
Figure 30. EVAL-ADAQ23875FMCZ Board Secondary Silkscreen
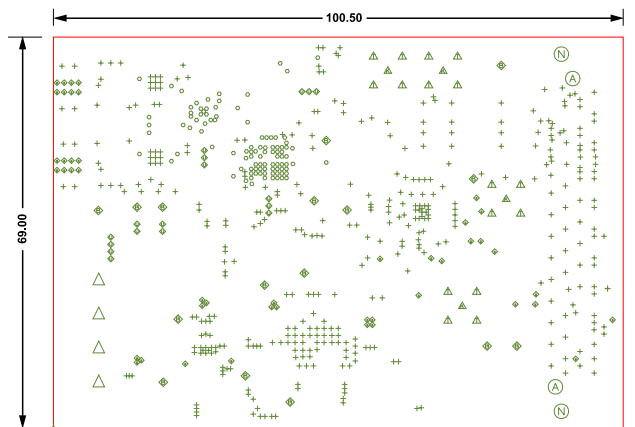
Figure 31. EVAL-ADAQ23875FMCZ Board Drill Chart and Size 69 mm × 100.5 mm

ORDERING INFORMATION

BILL OF MATERIALS

Table 5. Bill of Materials

Qty	Reference Designator	Description	Part No.	Manufacturing
4	+3P3V, AMPWR+, AMPWR−, GND	Connector PCB solder terminal turrets	2501-2-00-80-00-00-07-0	Mill-max
2	+4899, −4899	Connector PCB test point, red	5000	Keystone Electronics
2	A2, A3	Unity-gain stable, ultra low distortion	ADA4899-1YRDZ	Analog Devices
4	C1, C2, C9, C47	2.2 µF ceramic capacitor, X5R, general-purpose	GRM188R61H225KE11J	Murata
4	C3, C4, C7, C10	0.1 µF ceramic capacitor, X7R, 0603	06035C104KAT2A	AVX
1	C11	0.01 µF ceramic capacitor, X7R, automotive grade	C0603C103K5RECAUTO	Kemet
8	C13, C14, C17, C18, C19, C20, C21, C22	0.1 µF ceramic capacitor, X7R	06035C104J4Z2A	AVX
7	C26, C27, C28, C41, C42, C46, C86	10 µF ceramic capacitor, X5R, general-purpose	GRM188R61E106KA73D	Murata
2	C31, C35	4.7 µF ceramic capacitor, X5R, commercial grade	C0603C475K8PACTU	Kemet
2	C36, C43	47 µF ceramic capacitor, X5R, general-purpose	GRM188R60J476ME15D	Murata
2	C37, C38	4.7 µF ceramic multilayer capacitor, X5R	CC0805KKX5R8BB475	Yageo
1	C44	22 µF ceramic capacitor, X5R, general-purpose	GRM188R61A226ME15D	Murata
1	C45	100 µF ceramic capacitor, X5R, general-purpose	GRM21BR60J107ME15K	Murata
2	C48, C56	4.7 µF ceramic capacitor, X6S, general-purpose	GRM188C81C475KE11D	Murata
1	C49	0.01 µF ceramic capacitor, chip C0G 0603	C0603C103J3GACTU	Kemet
1	C50	1 µF ceramic capacitor, X7R	0603YC105KAT2A	AVX
2	C52, C54	1 µF ceramic capacitor, X7R	885012206076	Wurth Elektronik
3	C55, C57, C58	2.2 µF ceramic capacitor, X7R, general-purpose	GRM188R71A225KE15D	Murata
2	C59, C61	0.1 µF ceramic capacitor, 0603 X7R	C0603C104K4RAC	Kemet
9	C60, C62, C63, C70, C71, C72, C73, C74, C75	0.1 µF ceramic capacitor, X7R	C0402C104K4RACTU	Kemet
2	C64, C65	1 nF ceramic capacitor, 1 NF 5%, 50 V, C0G NP0 0402	C0402C102J5GACTU	Kemet
4	C66, C67, C68, C69	10 µF ceramic capacitor, X5R	C1608X5R1A106K080AC	TDK
1	C76	10 pF multilayer ceramic capacitor, C0G	C1608C0G1H100D080DA	TDK
1	C77	22 µF ceramic capacitor, X5R	C1608X5R0J226M080AC	TDK
1	C8	10 µF v X7R	C3216X7R1V106M160AC	TDK
1	DS2	LED green clear	QTLP600C4TR	Fairchild Semiconductor
1	E1	600 Ω at 100 MHz inductor chip ferrite bead	MPZ2012S601AT000	TDK
5	E2, E3, E4, E5, E6	30 Ω at 100 MHz inductor chip ferrite bead	BLM15PD300SN1D	Murata
4	GND1, GND2, GND3, GND4	Connector PCB test point, black	20-2137	Vero Technologies
1	J3	Connector PCB straight SMA PCB die cast	5-1814832-2	TE Connectivity
5	JP3, JP4, JP5, JP6, JP9	0 Ω resistor, Jumper R0402	ERJ-2GE0R00X	Panasonic
3	P1, P4, P6	Connector PCB, micro low profile terminal strips	FTS-103-01-F-S	Samtec
4	P2, P3, P7, P8	Connector PCB micro low profile terminal strips, 1.27 mm pitch	FTS-102-01-F-S	Samtec
1	P5	Connector PCB single end array male 160 positions	ASP-134604-01	Samtec
1	R10	150 kΩ resistor precision thick film chip, R0603	ERJ-3EKF1503V	Panasonic
1	R11	49.9 kΩ resistor precision thick film chip	ERJ-3EKF4992V	Panasonic
2	R13, R15	1 kΩ resistor precision thick film chip	MC0063W060311K	Multicomp
15	R7, R9, R14, R16, R21, R22, R24, R26, R28, R29, R30, R48, R52, R83, R87, R93, R94, R95	0 Ω resistor precision thick film chip, 0603	MC0603WG00000T5E-TC	Multicomp
3	R33, R34, R73	100 Ω resistor precision thick film chip	ERJ-1GNF1000C	Panasonic
1	R35	80.6 kΩ resistor precision thick film chip	CRCW060380K6FKEA	Vishay

ORDERING INFORMATION

Table 5. Bill of Materials

Qty	Reference Designator	Description	Part No.	Manufacturing
16	R36, R40, R41, R42, R61, R62, R63,R64, R65, R66, R67, R68, R69, R70, R71, R72	0 Ω resistor precision thick film chip	MC00625W040210R	Multicomp
1	R37	137 kΩ resistor precision thick film chip	MC0063W06031137K	Multicomp
1	R38	30.1 kΩ resistor precision thick film chip, R0603	ERJ-3EKF3012V	Panasonic
1	R39	75 kΩ resistor precision thick film chip, 0603	ERJ-3EKF7502V	Panasonic
1	R44	649 kΩ resistor precision thick film chip	ERJ-2RKF6493X	Panasonic
1	R45	210 kΩ resistor precision thick film chip	CPF0402B210KE1	TE Connectivity
1	R46	953 kΩ resistor precision thick film chip, 0805	9C08052A9533FKHFT	Yageo
1	R47	200 kΩ resistor precision thick film chip	ERJ-2RKF2003X	Panasonic
3	R53, R58, R60	33 Ω resistor precision thick film chip, 0603	MC0.063W06031%33R.	Multicomp
1	R54	49.9 Ω resistor precision thick film chip, R0603	ERJ-3EKF49R9V	Panasonic
2	R56, R57	1 kΩ resistor precision thick film chip, R0603	ERJ-3EKF1001V	Panasonic
1	R74	4.12 kΩ resistor precision thick film chip	ERJ-2RKF4121X	Panasonic
1	R76	Do not install	TBD0402	Panasonic
1	R79	10 Ω resistor precision thick film chip, R0603	ERJ-3EKF10R0V	Panasonic
1	R80	91 Ω resistor precision thick film	RC0603FR-0791RL	Yageo
1	R84	2.4 kΩ resistor precision thick film chip, R0603	ERJ-3EKF2401V	Panasonic
1	T1	Transformer RF 1:1	MABA-007159-000000	Macom Technology Solutions
1	U1	16-bit, 15 MSPS μModule data acquisition	ADAQ23875BBCZ	Analog Devices
1	U2	CMOS 3 V/5 V wide bandwidth, quad 2:1 mux	ADG774ABCPZ	Analog Devices
1	U10	TTL FF D-type positive edge	NL17SZ74USG	ON Semiconductor
1	U11	Low voltage, dual supply 2-bit signal translator	FXL2TD245L10X	ON Semiconductor
2	U9, U12	CMOS tiny logic high speed inverter	NC7S04M5X	Fairchild Semiconductor
1	U13	800 MHz clock distribution	AD9513BCPZ	Analog Devices
1	U14	2 kB serial I^2C bus EEPROM, 1.8 V to 5.5 V	M24C02-RMN6TP	ST Micro Electronics
1	U3	Ultra low noise, high accuracy voltage reference	ADR4520ARZ	Analog Devices
1	U4	Low noise, CMOS LDO linear regulator	ADP7118AUJZ-2.5-R7	Analog Devices
1	U5	0.25 ppm noise, low drift precision reference, 4.096 V out	LTC6655BHMS8-4.096#PBF	Analog Devices
1	U6	Dual SEPIC, inverting μModule dc-to-dc converter	LTM8049EY#PBF	Analog Devices
1	U7	Ultra low noise, high PSRR, LDO, adjustable voltage output	ADP7183ACPZN-R7	Analog Devices
1	U8	LDO, low noise, micropower regulator	LT3023IDD#PBF	Analog Devices
2	VIN+, VIN−	Connector PCB end launch SMA edge mount	142-0761-841	Cinch Connectivity Solutions
1	Y1	Crystal ultra low phase noise oscillator	CCHD-575-50-100.000	Crystek Corporations.
10	+2P5V, +5V, +6P5V, +7V, −2P5V, −2V, 3P3VAX, TP15, TSTMOD, TSTPAT	Connector PCB test point, red	5000	Keystone Electronics
7	C24, C25, C29, C39, C40	Do not install	TBD0402	TBD
2	C15, C16	0.1 μF ceramic capacitor, X7R	06035C104J4Z2A	AVX Corporation
4	C5, C6, C79, C80	Do not install	TBD0603	TBD
3	J1, J2, J4	Connector PCB straight SMA die cast	5-1814832-2	TE Connectivity LTD
14	R1, R2, R4, R5, R12, R23, R31, R32, R49, R85, R86, R89, R90, R91, R92,	Do not install, 0 Ω resistor precision thick film chip, 0603	MC0603WG00000T5E-TC	Multicomp
4	R17, R18, R19, R20	82 Ω resistor precision thick film chip	RGH1608-2C-P-820-B	Susumu CO, LTD
1	R3	Do not install	TBD0603	TBD
4	R43, R75	Do not install	TBD0402	TBD
6	R55, R59, R77, R78, R81, R82	10 kΩ resistor precision thick film chip R0603	ERJ-3EKF1002V	Panasonic
2	R6, R8	0 Ω resistor precision thick film chip	MC00625W040210R	Multicomp

ORDERING INFORMATION

NOTES

ESD Caution

ESD (electrostatic discharge) sensitive device. Charged devices and circuit boards can discharge without detection. Although this product features patented or proprietary protection circuitry, damage may occur on devices subjected to high energy ESD. Therefore, proper ESD precautions should be taken to avoid performance degradation or loss of functionality.